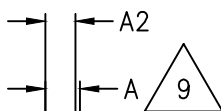
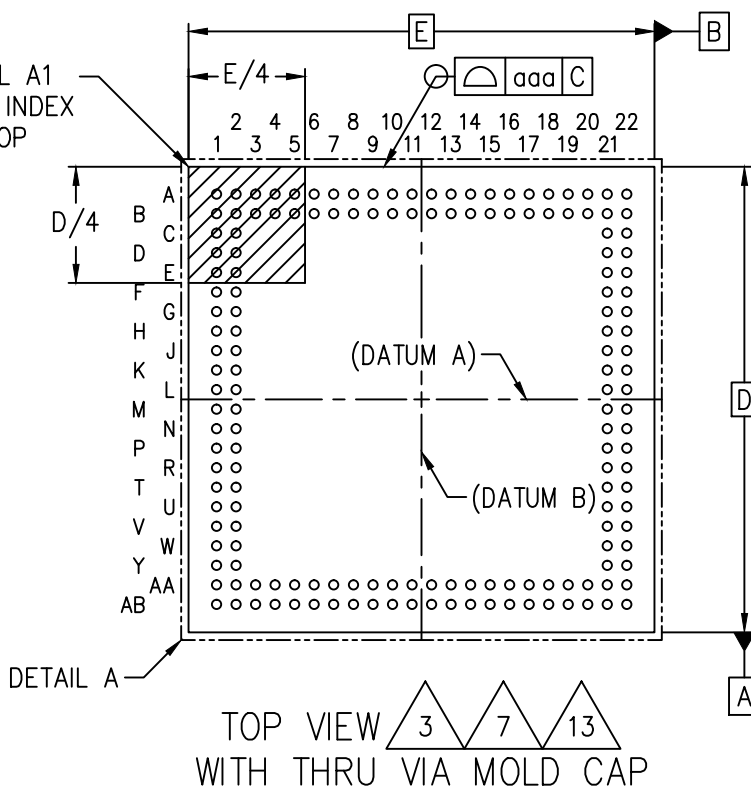


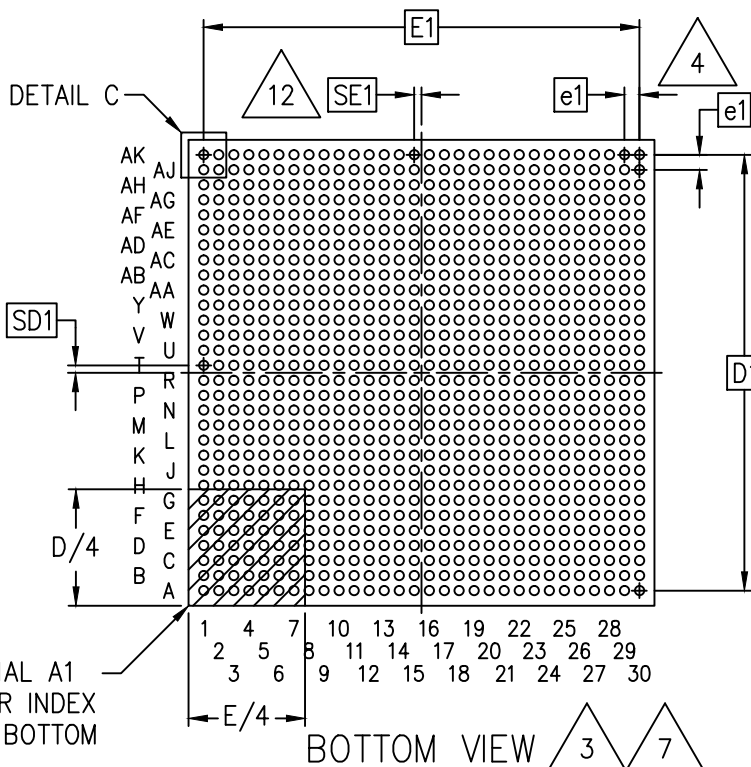
PATENT CLAIMS 16

IT IS REQUESTED THAT ANY FOOTPRINTS THAT ARE ADDED TO THIS MO ALSO BE ADDED TO THE CORRESPONDING UPPER POP PACKAGE.

11 TERMINAL A1 CORNER INDEX AREA, TOP



DETAIL B WITH THRU VIA MOLD CAP



12 SD1

11 TERMINAL A1 CORNER INDEX AREA, BOTTOM

JEDEC SOLID STATE
PRODUCT OUTLINE
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THIS **REGISTERED OUTLINE** HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

LOWER POP BALL GRID
ARRAY FAMILY, SQUARE,
0.65 MM TOP, 0.50 MM BOT PITCH

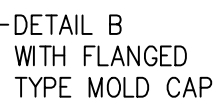
PACKAGE DESIGNATOR
S-XBGA

ITEM
MO-325

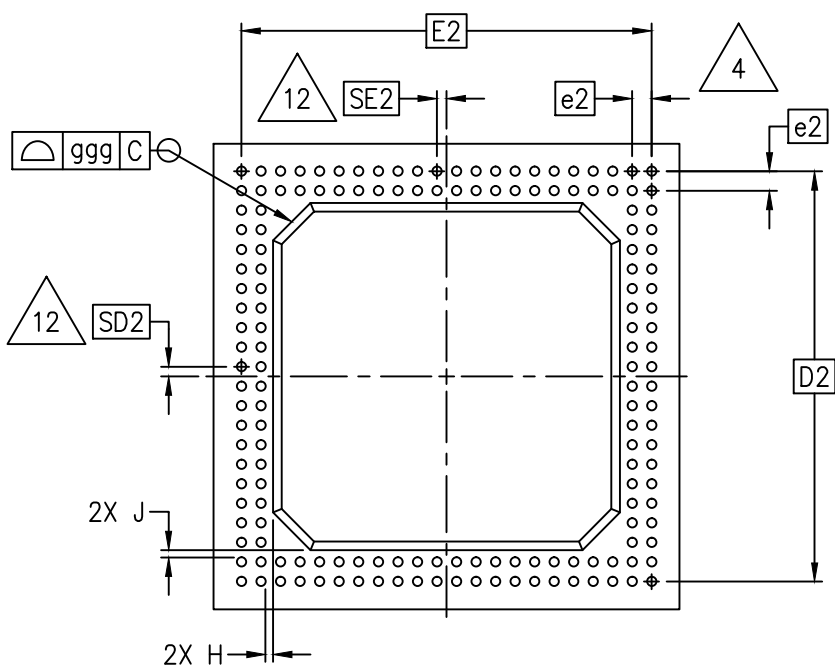
ISSUE
A

DATE
AUG 2016

SHEET
1 OF 14



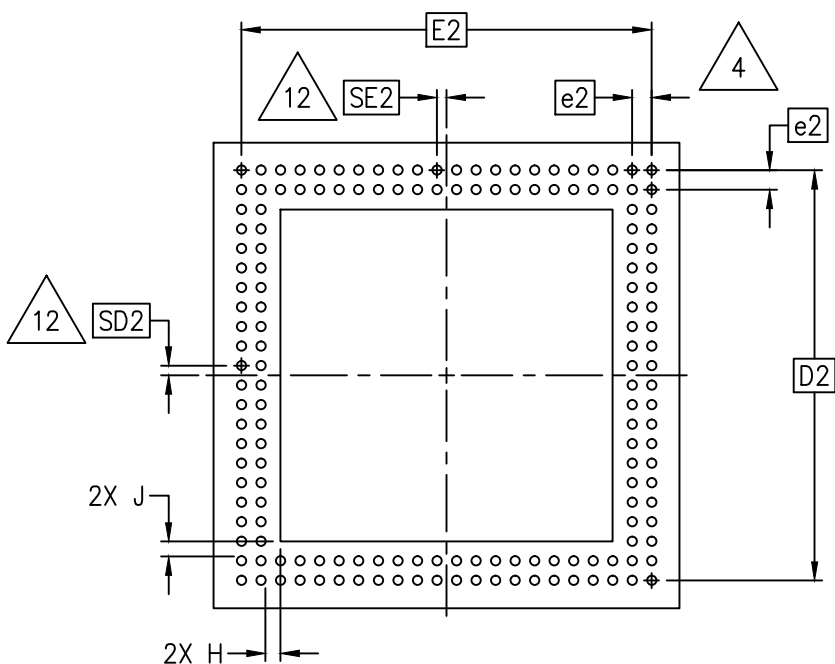
SIDE VIEW



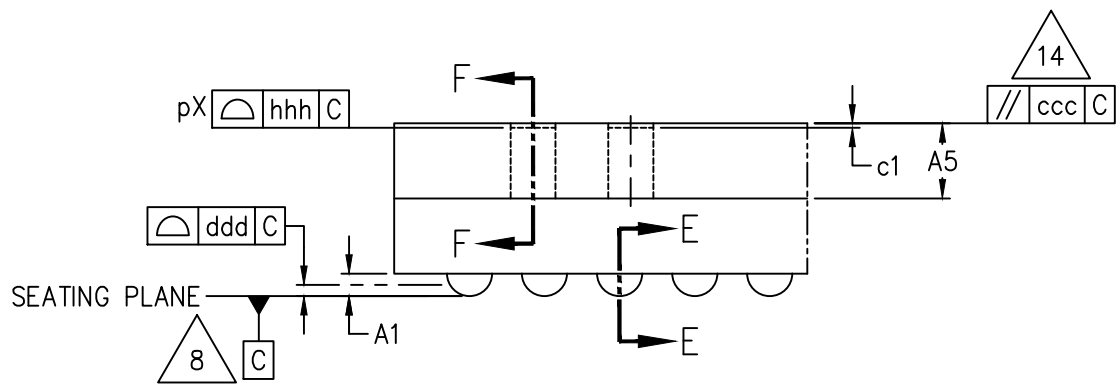
DETAIL A
WITH FLANGED TYPE MOLD CAP



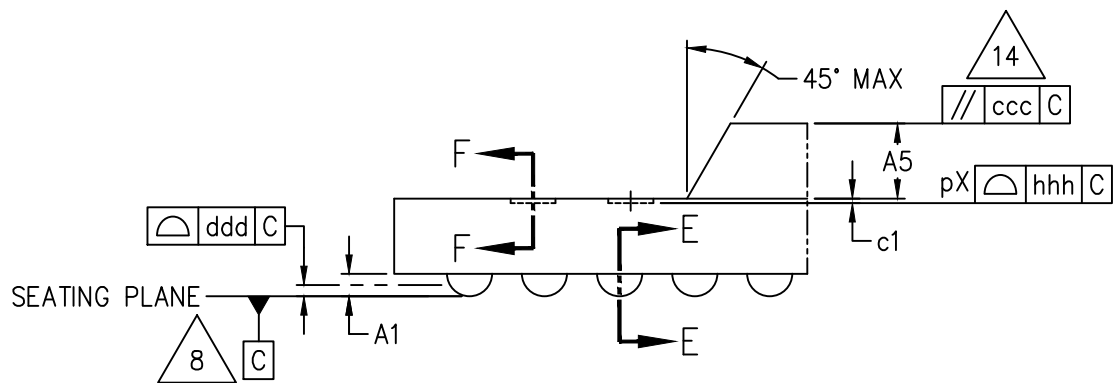
SIDE VIEW



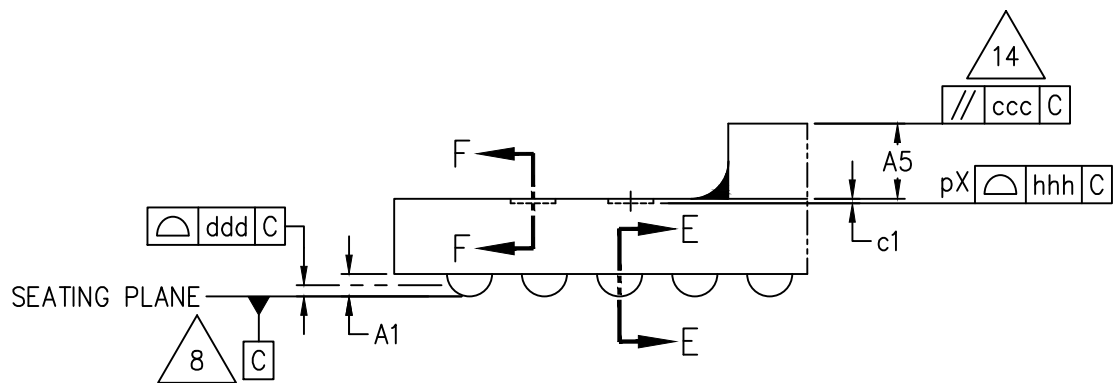
DETAIL A
WITH BARE DIE



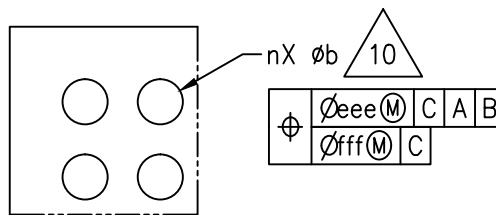
DETAIL B WITH THROUGH VIA MOLD CAP
(ROTATED 90° CW)



DETAIL B WITH FLANGED TYPE MOLD CAP
(ROTATED 90° CW)



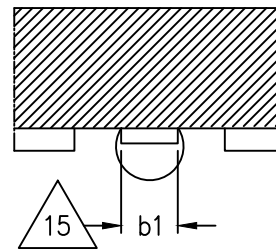
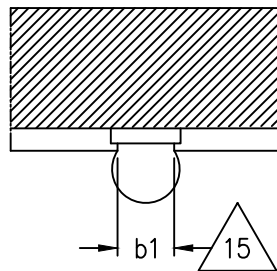
DETAIL B WITH BARE DIE
(ROTATED 90° CW)



DETAIL C
(PACKAGE BOTTOM)

TYPE 1 – SMD
(SOLDER MASK DEFINED)

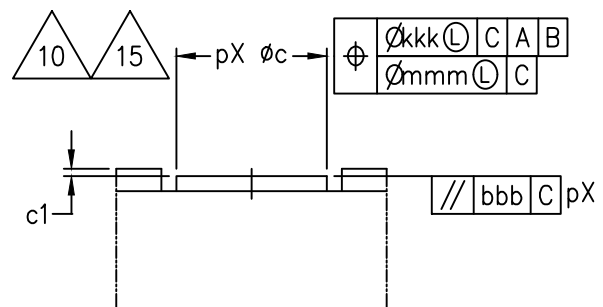
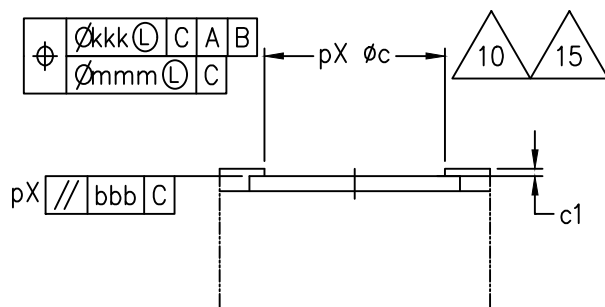
TYPE 2 – NSMD
(NON SOLDER MASK DEFINED)



SECTION E-E

TYPE 1 – SMD
(SOLDER MASK DEFINED)

TYPE 2 – NSMD
(NON SOLDER MASK DEFINED)



SECTION F-F

TABLE 1

COMMON DIMENSIONS						
SYMBOL	P = PACKAGE PROFILE HEIGHT					
	090			---		
	MIN	NOM	MAX	MIN	NOM	MAX
A	> 0.80	---	0.90	---	---	---
A2	---	---	0.75	---	---	---
A5	---	---	0.40	---	---	---
e1	0.50 BASIC					
e2	0.65 BASIC					
H	0.10	---	---	---	---	---
J	0.10	---	---	---	---	---
NOTES	1, 2, 4, 9, 18			-		
REF	11-927			-		
ISSUE	A			-		

TABLE 2

COMMON DIMENSIONS				
SYMBOL		(b) SOLDER BALL DIAMETER		
		MIN	NOM	MAX
A1		0.15	---	---
b		0.25	0.30	0.35
b1	TYPE 1	0.20	---	---
	TYPE 2	0.20	---	---
		(c) SOLDER LAND DIAMETER		
c		0.27	0.30	0.33
c1		---	---	0.40
NOTES		1, 2, 18		
REF		11-927		
ISSUE		A		